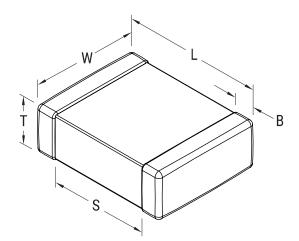


C1812X202F2TAC7210

SMD Comm X8G HT150C Flex, Ceramic, 2,000 pF, 1%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



Click here for the 3D model.

General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	67 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions		Specifications
Chip Size	1812	Capacitance
L	4.5mm +/-0.4mm	Measurement C
W	3.2mm +/-0.3mm	Tolerance
т	1mm +/-0.10mm	Voltage DC
S	2.3mm MIN	Dielectric Withs
В	0.7mm +/-0.35mm	Temperature Ra
		Temp. Coefficie
Packaging Specifications		

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	4000

Specifications	
Capacitance	2,000 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	1%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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